

# Epoxies, Ect. 20-3035 (Cat.140)

Epoxies; Epoxide

Epoxies, Etc.

## Message:

20-3035 is a low density, two component epoxy potting and encapsulating system. The 20-3035 is less than half the weight of most commercially available potting compounds.

20-3035 exhibits very low shrinkage during the cure cycle and also has a low coefficient of thermal expansion. This unique epoxy system is an ideal material for the potting of electronic assemblies where a low dielectric constant and low weight are required.

This epoxy syntactic foam system utilizes an advanced micro balloon technology filler. The 20-3035 provides high strength and stiffness, thermal and environmental stability, creep resistance, and water resistance.

Features:

- Low Dielectric Constant
- Low Coefficient of Thermal Expansion
- Low Shrinkage
- Low Density
- Excellent Moisture Resistance

General Information		
Features	Good Creep Resistance	
	Good Thermal Stability	
	High Stiffness	
	High Strength	
	Low Density	
	Low Shrinkage	
	Low to No Water Absorption	
Uses	Electrical/Electronic Applications	
Processing Method	Encapsulating	
	Potting	
Physical	Nominal Value	Unit
Molding Shrinkage - Flow	0.10	%
Mechanical	Nominal Value	Unit
Flexural Strength	34.5	MPa
Thermal	Nominal Value	Unit
CLTE - Flow	4.3E-5	cm/cm/°C
Thermal Conductivity	0.19	W/m/K
Thermoset	Nominal Value	Unit
Thermoset Mix Viscosity (25°C)	5000	cP
Additional Information	Nominal Value	Unit
Operating Temperature	-65.0 to 105	°C
Outgassing		
% CVC	0.0900	
% TMLV	0.740	

Uncured Properties	Nominal Value	Unit
Mix Ratio by Weight (PBW)		
Part A	100	
Part B	23	
Density (25°C)	0.838	g/cm <sup>3</sup>
Viscosity <sup>1</sup> (25°C)	45	Pa·s
Curing Time		
65°C	1.0 to 2.0	hr
45°C	4.0 to 6.0	hr
25°C	16 to 24	hr
Pot Life <sup>2</sup> (25°C)	30	min
Cured Properties	Nominal Value	Unit
Water Absorption <sup>3</sup>	0.40	%
Shore Hardness (Shore D)	78	
Tensile Strength	29.6	MPa
Compression Strength	68.9	MPa
Electric Strength	15	kV/mm
Relative Permittivity (1 MHz)	2.90	
Volume Resistivity (25°C)	> 1.0E+13	ohms·cm
Dissipation Factor (1 MHz)	0.050	
NOTE		
1.	Part A	
2.	100 grams	
3.	After 24 hours	

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#### Recommended distributors for this material

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